



- NOTES:
- PLATING THICKNESS  
 Ni:1.27~8.89 MICRON. (SOLDER PADS)  
 Au:0.30 MICRON MIN.  
 (EXCEPT 0.30~1.00 MICRON AT SOLDER PADS.)
  - CONNECTION.  
 (A-C-5), (B-D-6), (E-2-S/R), (F-3), (G-J-4), (H-1), (7-N/C), (8-N/C)
  - CAMBER : 50.00 MICRON MAX.
  - MBTALLIZATION RUNDOWN 0.20 MAX.
  - EXPOSURE OF CERAMIC SURFACE AND METALLIZED PATTERN OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
  - PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
  - STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
  - SEALING METHOD OF THIS PRODUCT SHALL BE SEAM WELD.

TOLERANCE	REVISION	SEE ATTACHED EXCEPTIONS SHEET.				TITLE	
±1% N.L.T.±0.13 ANGLES	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	7050 OSC C1 DLD	
	12 : 1	mm	3rd			PART NO.	REV.
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	S5070CLK7	0
90%MIN.A1203 (NA-31B BLACK)	Sumida	Kamitamaru	Miyata	Ano	Sakima	DWG NO.	SHT/OF
			May.19.05	May.19.05	May.19.05		1/6